

# LTM8020 21LD 6.25mm X 6.25mm X 2.32mm (TABLE OF MATERIAL DECLARATION)

*The LTM8020 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0388	Barium Compounds	7727-43-7	0.0006	1.5000
				Filler Substances (Silica Crystalline)	73776-74-4	0.0155	39.9146
				Copper Metal	7631-86-9		
				Copper Compounds	7440-50-8	0.0217	56.0000
				Ecotoxic substances	1328-53-6	0.0000	0.0180
				Gold metal or alloy	7439-92-1	0.0000	0.0004
				Nickel	7440-57-5	0.0002	0.4600
				Zinc	7440-02-0	0.0008	2.1000
2	Solder Paste	Alloy	0.0055		7440-66-6	0.0000	0.0070
				Sn	7440-31-5	0.0052	95.0000
				Sb	7440-36-0	0.0003	5.0000
3	Passive/Active Components		0.0780	Ni Oxide	1313-99-1	0.0045	5.71
				Cu Oxide	1317-38-0	0.0015	1.92
				Zn Oxide	1314-13-2	0.0068	8.69
				Fe Oxide	1309-37-1	0.0247	31.68
				iron Powder (Fe)	7439-89-6	0.0007	0.93
				Copper (Cu)	7440-50-8	0.0189	24.23
				Nickel (Ni)	7440-02-0	0.0024	3.06
				Tin (Sn)	7440-31-5	0.0014	1.77
Ceramic (Ba Compounds)	12047-27-7	0.0172	22.01				
4	Active Ics	Silicon	0.0004	Silicon	7440-21-3	0.0004	100.0000
5	Wire	Gold	0.0002	Au	7440-57-5	0.0002	99.9900
6	Encapsulation	Epoxy Resin	0.1251	Fused Silica	60676-86-0	0.0966	77.2000
				Epoxy Resin	non-disclosure	0.0111	8.9000
				Phenol Resin	non-disclosure	0.0111	8.9000
				Crytalline Silica	14808-60-7	0.0038	3.0000
				Carbon Black	1333-86-4	0.0006	0.5000
				Metal Hydroxide	non-disclosure	0.0019	1.5000
Total Package Weight			0.2480				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts